12 2/2X 2 REC	U.S. Department of Com Patent and Trademark
To the Honorable Commissioner of Patents and Trademarks. Please	2648617
Name of conveying party(ies):	Name and Address of receiving party(ies):
Thanh T. Tran	
Than I. Tan	Name: Texas Instruments Incorporated
Additional name(s) & address(es)	Address: P.O. Box 655474, M/S 3999
attached? Yes X No	City: Dallas
	State: <b>Texas</b> Zip: <b>75265</b> Additional name(s) & address(es) attached? YesX No
3. Nature of Conveyance:	
X Assignment Merger	
Security Agreement Change of Name	
Other	
Execution Date: December 22, 2003	
A. Patent Application No.(s) 10749501	B. Patent No.(s)
Additional numbers attached?Yes _X_ No	Additional numbers attached? YesX No
Name and address of party to whom correspondence concerning document should be mailed:	Number of applications and patents involved: _1_
Name: Mike Skrehot	
Address: Texas Instruments Incorporated P.O. Box 655474, M/S 3999	
City: Dallas	
State: Texas Zip: 75265	
	7. Amount of fee enclosed or authorized to be charged: \$
	8. Deposit account number: 20-0668
DO NOT US	SE THIS SPACE
9. Statement and signature.  To the best of my knowledge and belief, the foregoing information document.  Barry W. Dove, 1	
Signature Name of Per	
04 ECOOPER 00000145 200668 10749501	

Total number of pages including cover sheet, attachments and document:

Attorney Docket No.

## ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with its principal office at 7839 Churchill Way, M.S. 3999, Dallas, Texas 75251, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;		
TITLE OF INVENTION	Non-Uniform Decoupling Capacitor Distribution for Providing More Uniform Noise Reduction Across Chip	
SIGNATURE OF INVENTOR AND NAME	(1) Thanh T. Tran	
DATE	12-28-03	
RESIDENCE (CITY AND STATE)	Houston, TX	
DATE APPLICATION EXECUTED	12-22-03	

After recording, return Assignment to:

**RECORDED: 12/31/2003** 

Mike Skrehot Texas Instruments Incorporated P.O. Box 655474, M/S 3999 Dallas, TX 75265

> PATENT REEL: 014881 FRAME: 0035